2SK2315

Silicon N-Channel MOS FET

HITACHI

Application

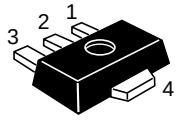
High speed power switching

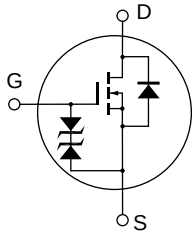
Features

- Low on-resistance
- High speed switching
- Low drive current
- 2.5 V gate drive device can be driven from 3 V source.
- Suitable for DC-DC converter, motor drive, power switch, solenoid drive

Outline

UPAK





1. Gate
2. Drain
3. Source
4. Drain

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Absolute Maximum Ratings (Ta = 25°C)

Item	Symbol	Ratings	Unit
Drain to source voltage	V_{DSS}	60	V
Gate to source voltage	V_{GSS}	±20	V
Drain current	I_D	2	A
Drain peak current	$I_{D(pulse)}$*[1]	4	A
Body to drain diode reverse drain current	I_{DR}	2	A
Channel dissipation	Pch*[2]	1	W
Channel temperature	Tch	150	°C
Storage temperature	Tstg	–55 to +150	°C

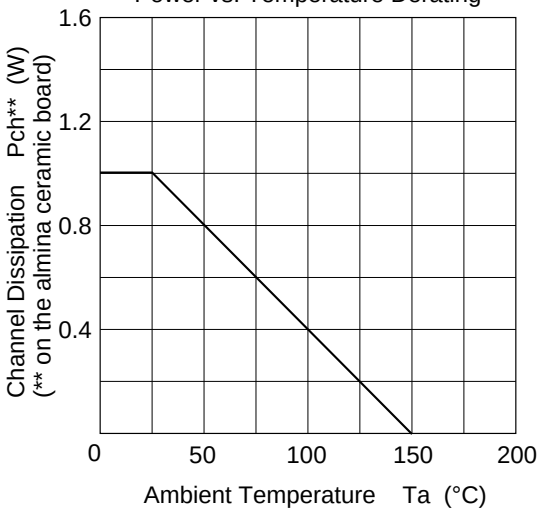
Notes 1. PW ≤ 10 µs, duty cycle ≤ 1 %
2. When using the alumina ceramic board (12.5 × 20 × 0.7mm)
3. Marking is “TY”

Electrical Characteristics (Ta = 25°C)

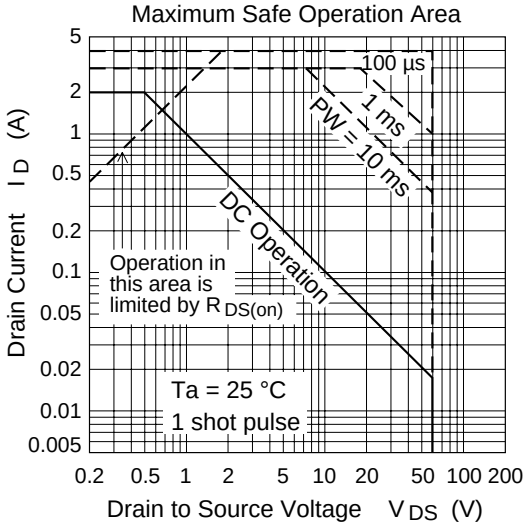
Item	Symbol	Min	Typ	Max	Unit	Test Conditions
Drain to source breakdown voltage	$V_{(BR)DSS}$	60	—	—	V	I_D = 10 mA, V_{GS} = 0
Gate to source breakdown voltage	$V_{(BR)GSS}$	±20	—	—	V	I_G = ±100 µA, V_{DS} = 0
Gate to source leak current	I_{GSS}	—	—	±5	µA	V_{GS} = ±16 V, V_{DS} = 0
Zero gate voltage drain current	I_{DSS}	—	—	5	µA	V_{DS} = 50 V, V_{GS} = 0
Gate to source cutoff voltage	$V_{GS(off)}$	0.5	—	1.5	V	I_D = 1 mA, V_{DS} = 10 V
Static drain to source on state resistance	$R_{DS(on)}$	—	0.4	0.6	Ω	I_D = 0.3 A V_{GS} = 3 V*[1]
		—	0.35	0.45	Ω	I_D = 1 A V_{GS} = 4 V*[1]
Forward transfer admittance	$\|y_{fs}\|$	1.5	1.8	—	S	I_D = 1 A V_{DS} = 10 V*[1]
Input capacitance	Ciss	—	173	—	pF	V_{DS} = 10 V
Output capacitance	Coss	—	85	—	pF	V_{GS} = 0
Reverse transfer capacitance	Crss	—	23	—	pF	f = 1 MHz
Turn-on time	t_{on}	—	21	—	ns	I_D = 1 A, R_L = 30 Ω
Turn-off time	t_{off}	—	85	—	ns	V_{GS} = 10 V

Note 1. Pulse Test

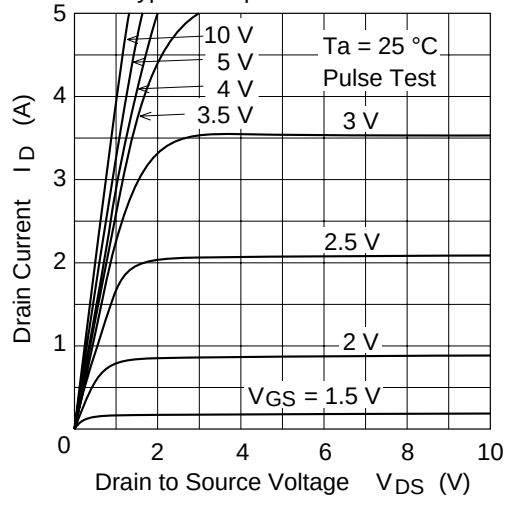
Power vs. Temperature Derating



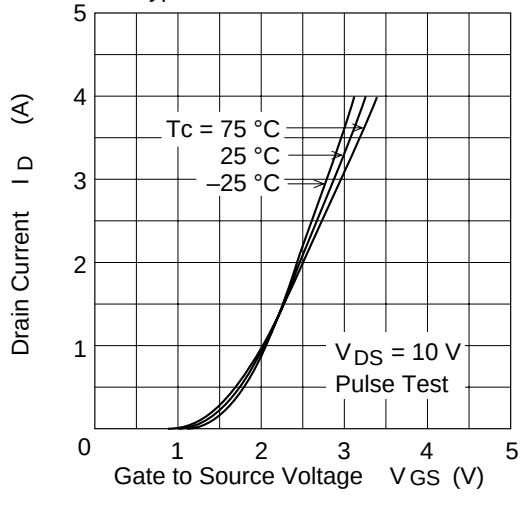
Maximum Safe Operation Area



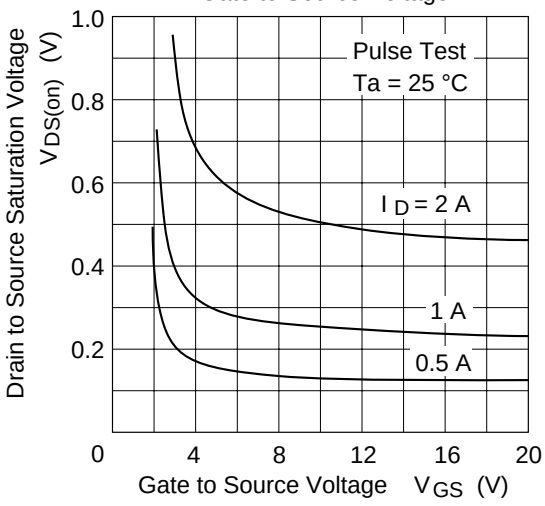
Typical Output Characteristics



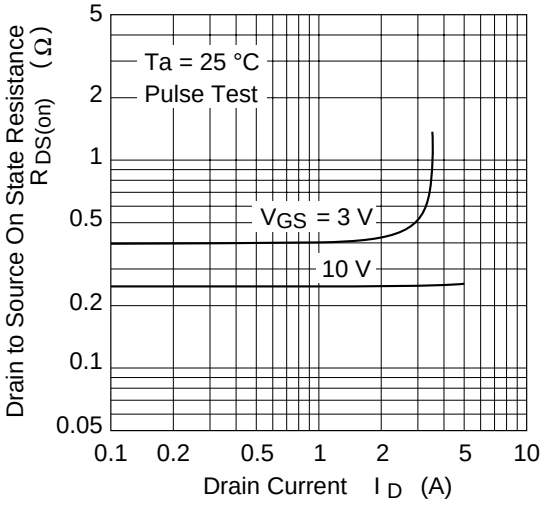
Typical Transfer Characteristics



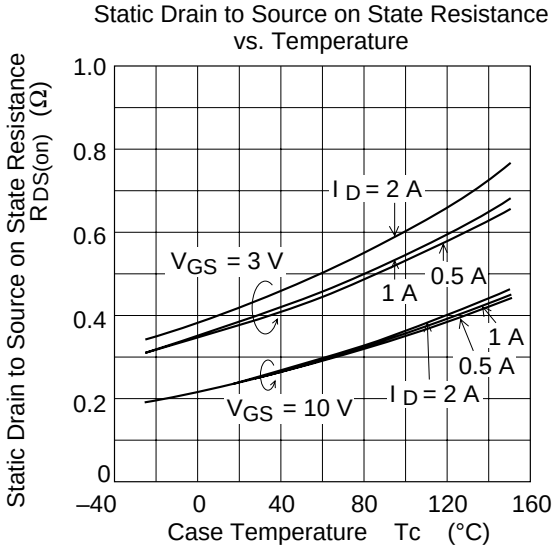
Drain to Source Saturation Voltage vs. Gate to Source Voltage



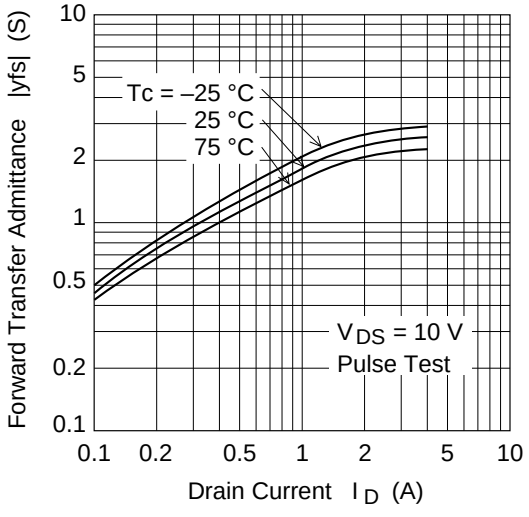
Static Drain to Source State Resistance vs. Drain Current



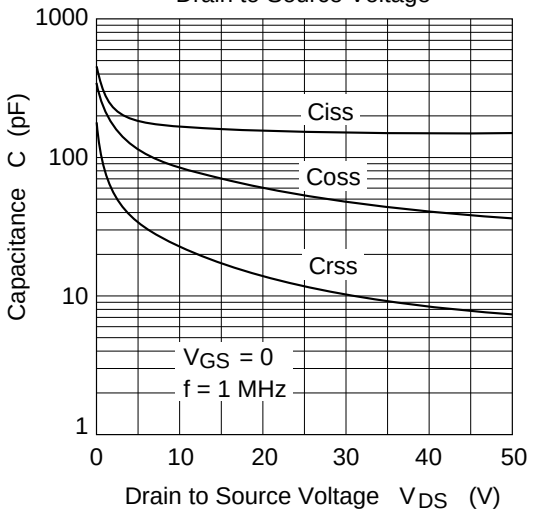
Static Drain to Source on State Resistance vs. Temperature



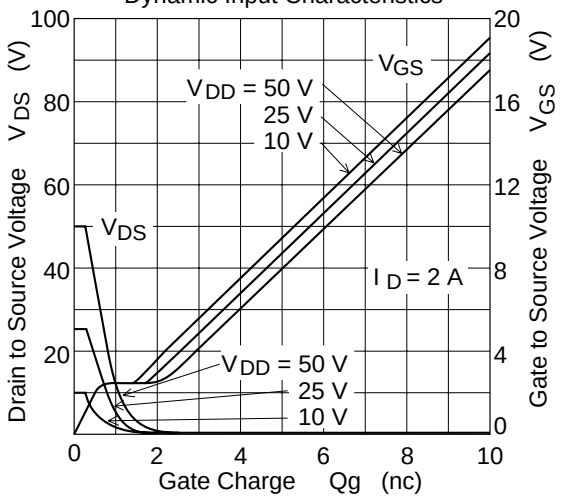
Forward Transfer Admittance vs. Drain Current



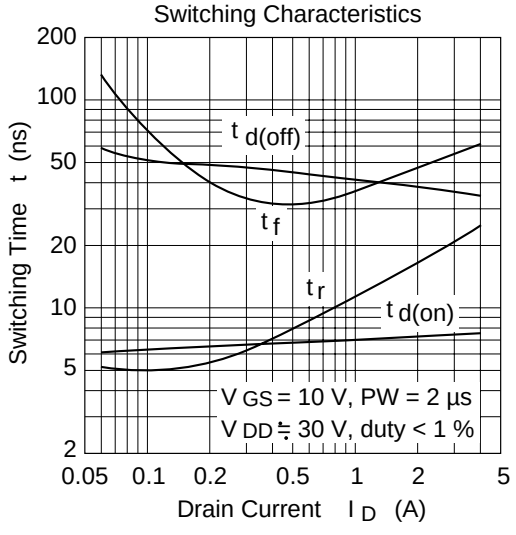
Typical Capacitance vs.
Drain to Source Voltage



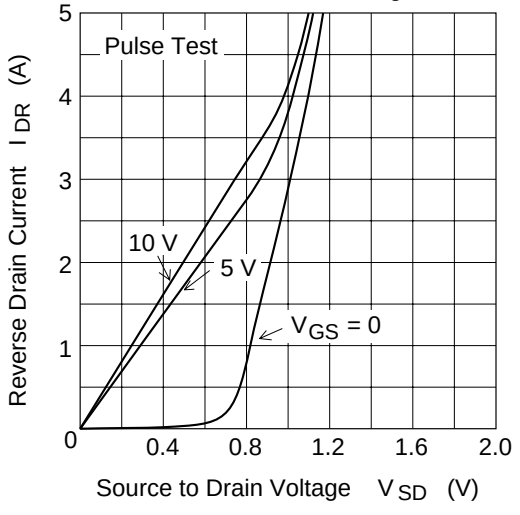
Dynamic Input Characteristics



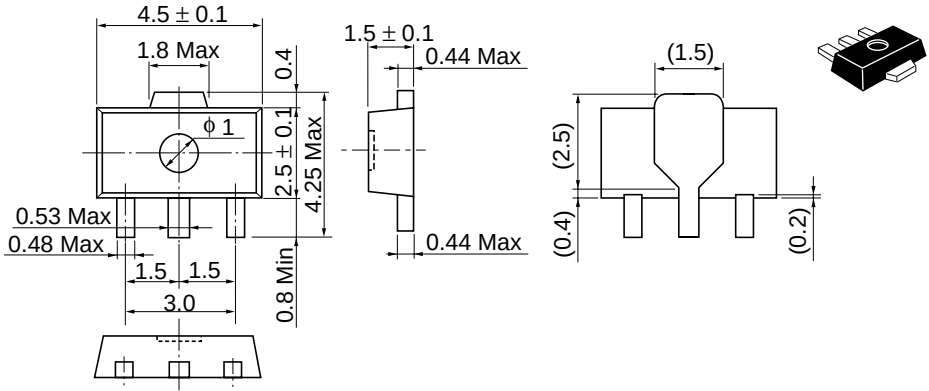
Switching Characteristics



Reverse Drain Current vs.
Souece to Drain Voltage



Unit: mm



Hitachi Code	UPAK
JEDEC	—
EIAJ	Conforms
Weight (reference value)	0.050 g

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